

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT2929383

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YOSHIHIRO AKIMOTO	01/28/2011
SHOEI KOBAYASHI	01/28/2011
MOTOSHI ITO	06/22/2010
YASUMORI HINO	06/22/2010
HIROYASU INOUE	06/17/2010
HARUKAZU MIYAMOTO	07/05/2010
KOICHIRO NISHIMURA	07/01/2010
SUNG-HEE HWANG	02/01/2011
IN-OH HWANG	02/01/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SONY CORPORATION
<b>Street Address:</b>	1-7-1 KONAN, MINATO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	108-0075
<b>Name:</b>	PANASONIC CORPORATION
<b>Street Address:</b>	1006, OAZA KADOMA
<b>City:</b>	KADOMA-SHI, OSAKA
<b>State/Country:</b>	JAPAN
<b>Name:</b>	TDK CORPORATION
<b>Street Address:</b>	1-13-1, NIHONBASHI, CHUO-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Name:</b>	HITACHI CONSUMER ELECTRONICS CO., LTD.
<b>Street Address:</b>	2-1, OTEMACHI 2-CHOME, CHIYODA-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Name:</b>	SAMSUNG ELECTRONICS CO., LTD.
<b>Street Address:</b>	416, MAETAN-DONG, YEONGTONG-GU
<b>City:</b>	SUWON-SI, GYEONGGI-DO
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>PATENT</b>	

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	13060606

**CORRESPONDENCE DATA****Fax Number:** (703)413-2220*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***Phone:** (703) 413-3000**Email:** Mchanthaphone@oblon.com**Correspondent Name:** OBLON, SPIVAK, ET AL.**Address Line 1:** 1940 DUKE STREET**Address Line 4:** ALEXANDRIA, VIRGINIA 22314**ATTORNEY DOCKET NUMBER:** 357255US8XPCT**NAME OF SUBMITTER:** DANLEY, ROMON**SIGNATURE:** /Romon Danley/**DATE SIGNED:** 07/08/2014**Total Attachments: 15**

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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name are listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in  
RECORDABLE OPTICAL DISK, RECORDING DEVICE, AND RECORDING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, 108-0075 Japan, Panasonic Corporation, with offices at 1006, Oaza Kadoma, Kadoma-shi, Osaka, Japan, TDK Corporation, with offices at 1-13-1, Nihonbashi, Chuo-ku, Tokyo, Japan, Hitachi Consumer Electronics Co., Ltd., with offices at 2-1, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan and Samsung Electronics Co., Ltd., with offices at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (hereinafter referenced as ASSIGNEES) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or their designee, as ASSIGNEES or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

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And I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

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Filing Date: July 1, 2010

This assignment executed on the dates indicated below.

Yoshihiro AKIMOTO  
Name of first or sole inventor

January 28, 2011  
Execution date of U.S. Patent Application

Chiba, Japan  
Residence of first or sole inventor

*Yoshihiro Akimoto*  
Signature of first or sole inventor

January 28, 2011  
Date of this assignment

Shoei KOBAYASHI  
Name of second inventor

January 28, 2011  
Execution date of U.S. Patent Application

Kanagawa, Japan  
Residence of second inventor

*Shoei Kobayashi*  
Signature of second inventor

January 28, 2011  
Date of this assignment

Motoshi ITO  
Name of third inventor

Execution date of U.S. Patent Application

Osaka, Japan  
Residence of third inventor

Signature of third inventor

Date of this assignment

Yasumori HINO  
Name of fourth inventor

Execution date of U.S. Patent Application

Nara, Japan  
Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Hiroyasu INOUE  
Name of fifth inventor

Execution date of U.S. Patent Application

Nagano, Japan  
Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Harukazu MIYAMOTO  
Name of sixth inventor

Execution date of U.S. Patent Application

Tokyo, Japan  
Residence of sixth inventor

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Koichiro NISHIMURA

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Sung-hee HWANG

Name of eighth inventor

Execution date of U.S. Patent Application

Suwon-si, Korca

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Signature of eighth inventor

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In-oh HWANG

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Name of second inventor

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Kanagawa, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Motoshi ITO

Name of third inventor

Execution date of U.S. Patent Application

Osaka, Japan

Residence of third inventor

*Motoshi Ito*

22 June, 2010

Signature of third inventor

Date of this assignment

Yasumori HINO

Name of fourth inventor

Execution date of U.S. Patent Application

Nara, Japan

Residence of fourth inventor

*Yasumori Hino*

22 June, 2010

Signature of fourth inventor

Date of this assignment

Hiroyasu INOUE

Name of fifth inventor

Execution date of U.S. Patent Application

Nagano, Japan

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Harukazu MIYAMOTO

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Signature of first or sole inventor

Date of this assignment

Shoei KOBAYASHI

Name of second inventor

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Motoshi ITO

Name of third inventor

Execution date of U.S. Patent Application

Osaka, Japan

Residence of third inventor

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Yasumori HINO

Name of fourth inventor

Execution date of U.S. Patent Application

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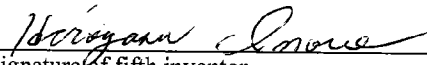
Hiroyasu INOUE

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Harukazu MIYAMOTO

Name of sixth inventor

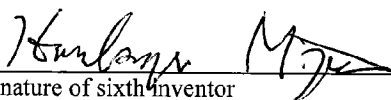
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7/5/2010

Koichiro NISHIMURA

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

*Koichiro Nishimura*

Signature of seventh inventor

*July 1, 2010*

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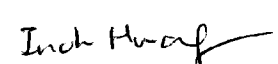
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